

Supplementary Information

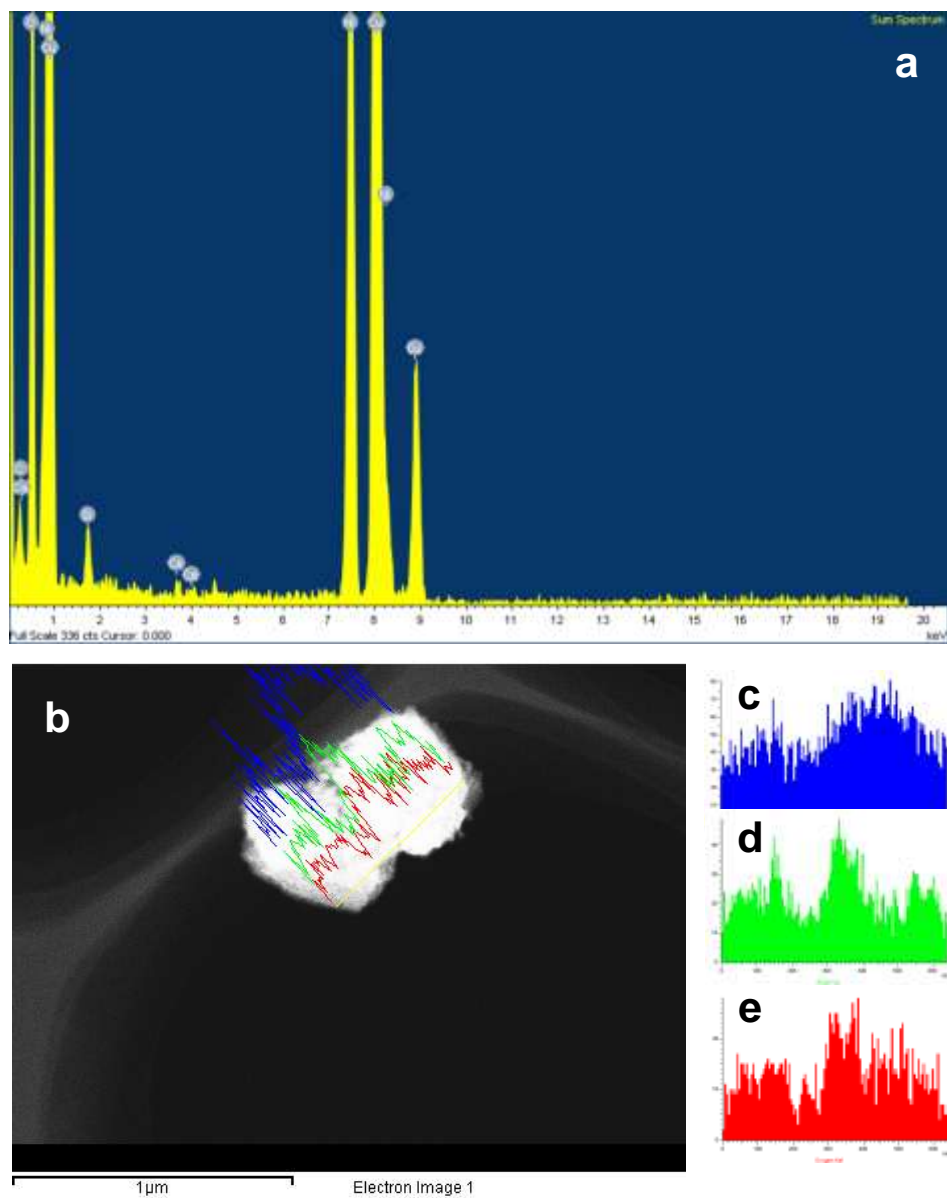
Mesoporous CuO-NiO Micropolyhedrons: Facile Synthesis, Morphological Evolution and Pseudocapacitive Performance

Yu Xin Zhang^{a,b,*}, Min Kuang^a, Jun Jie Wang^a

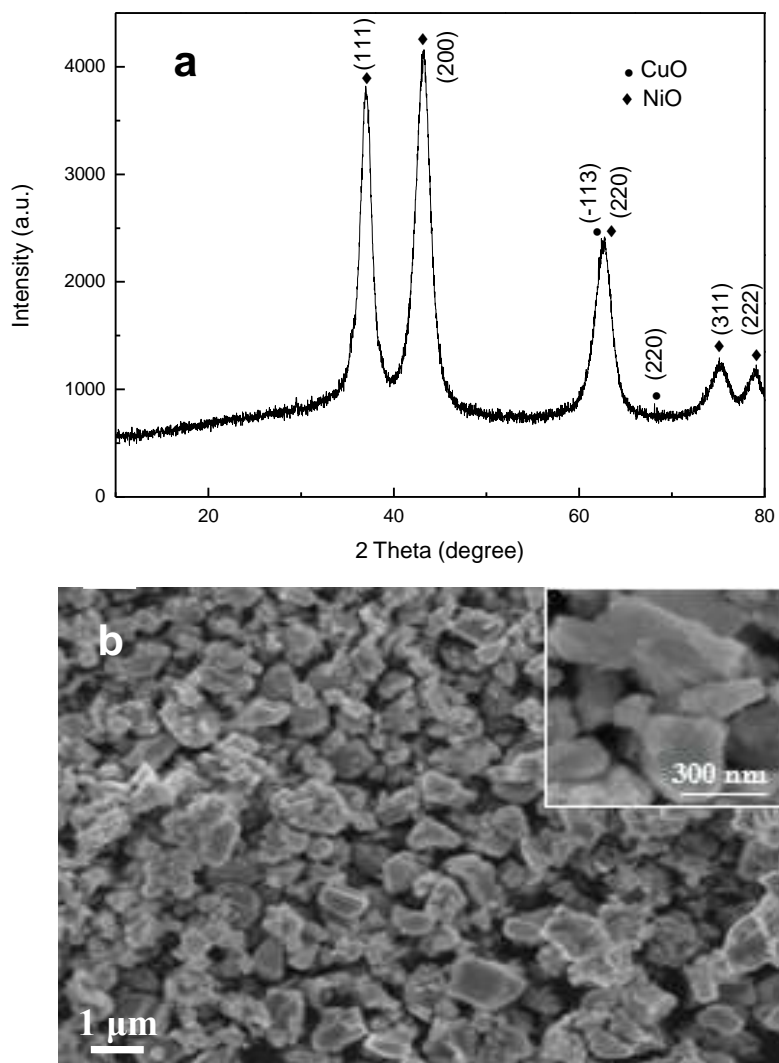
SI-1 The detailed synthetic conditions of various CuO-NiO composites

Sample	Cu(NO ₃) ₂ (mL)	Ni(NO ₃) ₂ (mL)	Na ₂ C ₂ O ₄ (mL)	EG (mL)	Time (h)	Temperature (°C)
Cu400	20	0	20	30	2	400
CuNi400(Cu/Ni=3)	15	5	20	30	2	400
CuNi400(Cu/Ni=1)	10	10	20	30	2	400
CuNi400(Cu/Ni=1/3)	5	15	20	30	2	400
CuNi350(Cu/Ni=1)	10	10	20	30	2	350
CuNi500(Cu/Ni=1)	10	10	20	30	2	500

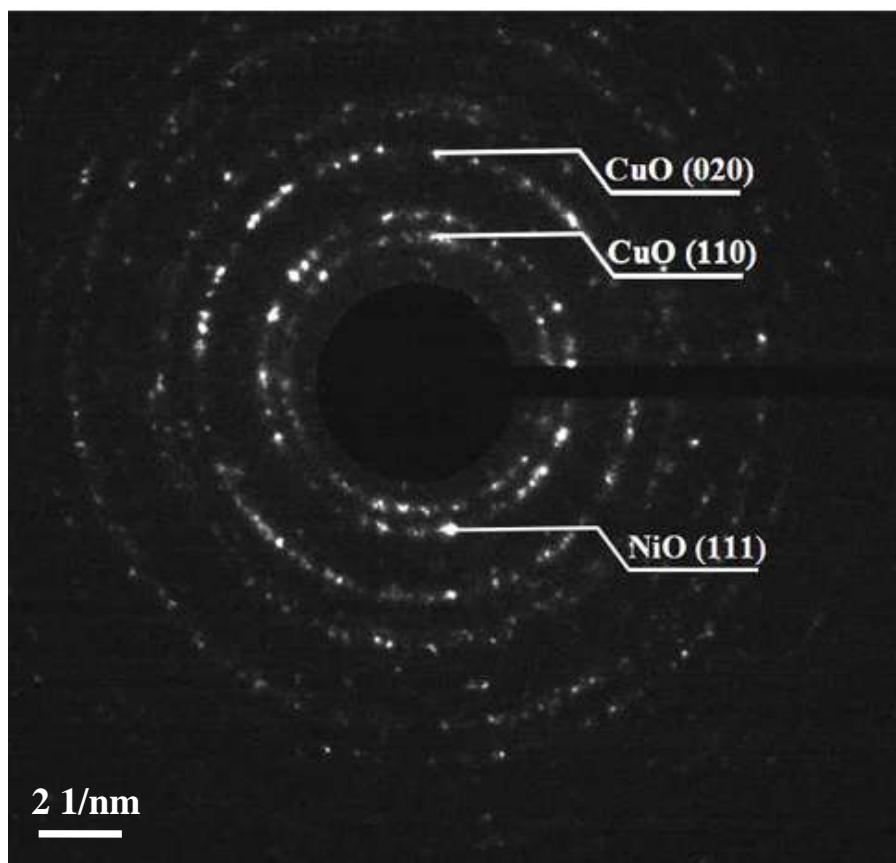
SI-2 TEM image for CuNi400(Cu/Ni=1) along with the line TEM EDX analysis (a and b), and the corresponding Cu (c), Ni (d) and O (e) line analyses TEM EDX.



SI-3 XRD pattern (a) and SEM image (b) of CuNi400 (Cu/Ni=1/3)



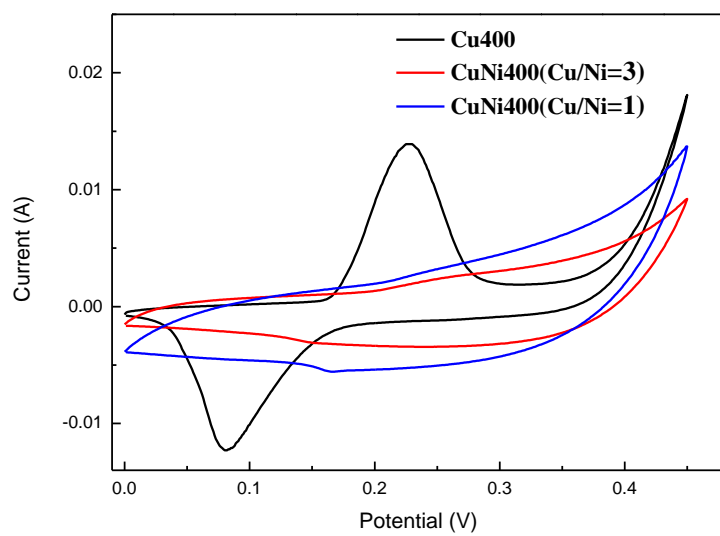
SI-4 The selected-area electron diffraction (SAED) pattern of CuO-NiO micropolyhedrons (CuNi400 (Cu/Ni=1)).



SI-5 Pore volume (V) for three samples obtained with different calcination temperature.

Sample	V (cm ³ /g)			
	Total	Micro- (<2 nm)	Meso- (2-50 nm)	Macro- (>50 nm)
CuNi350(Cu/Ni=1)	0.34	1.58%	58.16%	40.26%
CuNi400(Cu/Ni=1)	0.19	—	63.16%	36.84%
CuNi500(Cu/Ni=1)	0.13	—	36.6%	63.4%

SI-6 Cyclic voltammetry curves of Cu400, CuNi400(Cu/Ni=3) and CuNi400(Cu/Ni=1) at a scan rate of 5 mV s^{-1} .



SI-7 The galvanostatic charge-discharge curves of Cu400, CuNi400(Cu/Ni=3) and CuNi400(Cu/Ni=1) at a current density of 2 mA cm^{-2} .

